

PRODUCT DESCRIPTION

Modified epoxy | 1 part | solvent-free | thermal-curing | thermally conductive | electrically conductive

- ▶ Semiconductor technology
- ▶ LED bonding
- ▶ Electrically conductive bonding
- ▶ Very high filling density
- ▶ Good thermal conductivity
- ▶ Low ion content (Na+, K+, Cl- <10ppm)
- ▶ Silver filled

CURING PROPERTIES

This adhesive must be cured with heat. Typical curing temperatures are listed in the table below.

Temperatures	Time
150°C	30 min
180°C	15 min

The heat cure times are only provided as a guideline. They are derived from curing a 2g adhesive sample without affixed substrates in a laboratory environment. Actual cure times can vary based on part size, configuration, adhesive volume and temperature control required for the component substrates to attain oven temperature.

The final bond strength of the adhesive is achieved no sooner than 24 h after the bonded components are removed from the oven.

TECHNICAL DATASHEET

ELECOLIT® 3655



TECHNICAL DATA

Resin	Epoxy
Appearance	Grey
Filler	Silver
Filler - weight [%]	87
Particle size D90 [µm]	10
Particle size D100 [µm]	40
Uncured Material	
Viscosity [mPas] (Kinexus Rheometer, 25 °C, 10s ⁻¹) <i>Test instruction P064</i>	5,000 – 15,000
Thixotropic index [1/10] <i>Test instruction P064</i>	5 – 6
Density [g/cm ³] <i>Test instruction P004</i>	4.8 – 5.2
Cured Material	
Hardness shore D <i>Test instruction P006</i>	70 – 85
Typical operating temperature [°C]	-40 – 180
Linear shrinkage [%] <i>Test instruction P031</i>	<2
Water absorption [wt%] <i>Test instruction P016</i>	<1
Working life [h] <i>@ room temperature</i>	4
Glass transition temperature - DSC [°C] <i>Test instruction P009</i>	130 – 150
Coefficient of thermal expansion [ppm/K] below T _g <i>Test instruction P017</i>	30 – 60
Coefficient of thermal expansion [ppm/K] above T _g <i>Test instruction P017</i>	100 – 200
Thermal conductivity [W/m*K] <i>150°C, 30min</i> <i>Test instruction P062</i>	8.5 – 9.5
Thermal conductivity [W/m*K] <i>180°C, 1h</i> <i>Test instruction P062</i>	10 – 11
Volume resistivity [Ohm*cm] <i>150°C, 30min</i> <i>Test instruction P040</i>	1 x 10 ⁻⁴ – 3 x 10 ⁻⁴
Storage modulus – DMA [MPa] <i>150°C, 30min</i> <i>Test instruction P022</i>	1,000 – 1,600
Lap shear strength (silver/copper) [MPa] <i>150°C, 30min</i> <i>Test instruction P013</i>	22 – 27

TECHNICAL DATASHEET

ELECOLIT® 3655



Lap shear strength (silicium/copper) [MPa] <i>150°C, 30min</i> <i>Test instruction P013</i>	22 – 26
Lap shear strength (AgPd/copper) [MPa] <i>150°C, 30min</i> <i>Test instruction P013</i>	22 – 26
Die shear strength* (copper) [N/die] <i>150°C, 30min</i> <i>Test instruction P057</i>	120 – 160
Die shear strength* (AgPd/CuNiAu) [N/die] <i>150°C, 30min</i> <i>Test instruction P057</i>	240 – 300

***Si die 3x3mm (12x120mil)**

TRANSPORT/STORAGE/SHELF LIFE

Package type	Transport	Storage	Shelf life*
Syringe/Cartridge	-20°C	-20°C	At delivery min. 3 months max. 6 months
Other packages	0°C – 10°C	0°C – 10°C	

****Store in original, unopened containers!***

INSTRUCTIONS FOR USE

After storing the container at 0°C – 10°C, Elecolit® 3655 must be homogenized because of possible sedimentation of silver.

Surface preparation

The surfaces to be bonded should be free of dust, oil, grease, mold release, or other contaminants in order to obtain an optimal and reproducible bond. For cleaning we recommend the cleaner IP® from Hoenle, or a solution of Isopropyl Alcohol at 90% or higher concentration. Substrates with low surface energy (e.g. polyethylene, polypropylene) must be pretreated in order to achieve sufficient adhesion.

Application

Our products are supplied ready to use. Depending on the packaging, our adhesives may be dispensed by hand directly from the package, or they can be applied using dispensing systems and automation. Many commercially available valve and controller options are available to ensure accurate and consistent adhesive dispensing. For assistance with dispensing and curing questions, please contact our Applications Engineering department. Adhesive and substrate should not be cold for proper bonding. They must be allowed to warm to room temperature prior to processing. After curing, the adhesive must be allowed to cool to ambient temperature before testing the product's performance. For safety information refer to our Material Safety Data Sheet (MSDS)

Storage

Store uncured product in its original, closed container in a dry location. Any material removed from the original container must not be returned to the container as it could be contaminated. Hoenle cannot assume responsibility for products that were improperly stored, contaminated, or repackaged into other containers.

Handling and Clean-up

For safe handling information, consult this product's Material Safety Data Sheet (MSDS) prior to use. Uncured material may be wiped away from surfaces with organic solvents. Do not use solvents to remove material from eyes or skin!

DISCLAIMER

The product is free of heavy metals, PFOS and Phthalates and is conform to the current EU-Directive RoHS.

THE VALUES NOTED IN THIS TECHNICAL DATA SHEET ARE TYPICAL PROPERTIES AND ARE NOT MEANT TO BE USED AS PRODUCT SPECIFICATIONS.

The information contained in this data sheet is believed to be accurate and is provided for information only. Hoenle makes no representation or warranties of any kind concerning this information. It is the user's responsibility to determine the suitability of this product for any intended use. Hoenle does not assume responsibility for test or performance results obtained by the user. The user assumes all risk and liability connected with the use of this product.

The user should adopt such precautions and use guidelines as may be advisable for the protection of property and persons against any hazards that may be involved in this product's handling or use. Hoenle specifically disclaims any liability for consequential or incidental damages of any kind arising from the handling or use of this product. The information contained in this Technical Data Sheet offers no assurance that the product use, application, or process will not infringe on existing patents or licenses of others. Nothing in this Technical Data Sheet transfers or grants license for the use of any patents, trade secrets, intellectual property, or confidential information that is the property of Hoenle.

Except as otherwise noted, all trademarks in this document (identified as ®) are the property of Hoenle.

CONTACT

Hoenle Adhesives GmbH | Stierstädter Straße 4 | 61449 Steinbach | Germany

T: +49 6171 6202-0 | adhesivesystems@hoenle.com

For regional sales and technical support, please refer to our global contact directory

<https://www.hoenle.com/contact>.